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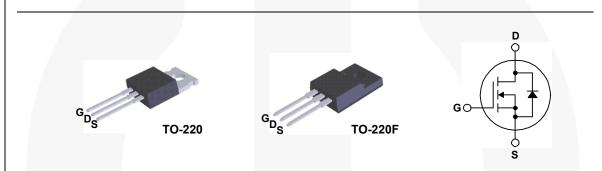
FQP6N90C / FQPF6N90C **N-Channel QFET® MOSFET** 900 V, 6.0 A, 2.3 Ω

Description

This N-Channel enhancement mode power MOSFET is • 6.0 A, 900 V, R_{DS(on)} = 2.3 Ω (Max.) @ V_{GS} = 10 V, produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state . Low Gate Charge (Typ. 30 nC) resistance, and to provide superior switching performance • Low Crss (Typ. 11 pF) and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power • 100% Avalanche Tested factor correction (PFC), and electronic lamp ballasts.

Features

- $I_{D} = 3.0 \text{ A}$



Absolute Maximum Ratings T_c = 25°C unless otherwise noted.

Symbol	Parameter	FQP6N90C	Unit		
V _{DSS}	Drain-Source Voltage	9	V		
I _D	Drain Current - Continuous ($T_C = 25^{\circ}C$)		6	6 *	А
	- Continuous (T _C = 100°C)		3.8	3.8 *	А
DM	Drain Current - Pulsed	(Note 1)	24	24 *	А
V _{GSS}	Gate-Source Voltage	±	V		
E _{AS}	Single Pulsed Avalanche Energy	6	mJ		
AR	Avalanche Current	(Note 1)	6		А
E _{AR}	Repetitive Avalanche Energy (Note 1)		10	mJ	
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5		V/ns
PD	Power Dissipation ($T_C = 25^{\circ}C$)	167	56	W	
	- Derate above 25°C	1.43	0.48	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to	°C		
TL	Maximum lead temperature for soldering, 1/8" from case for 5 seconds		3	°C	

* Drain current limited by maximum junction temperature.

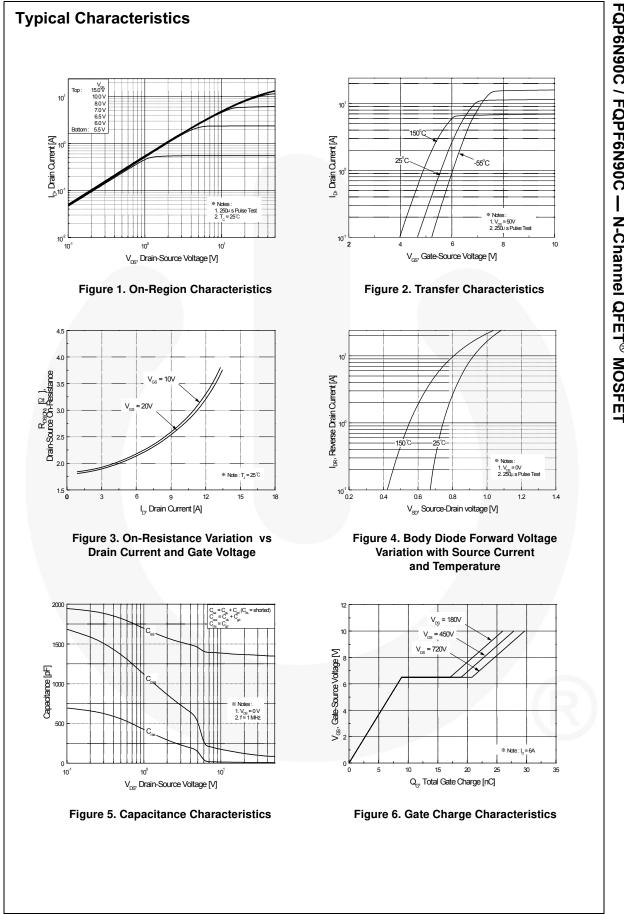
Thermal Characteristics

Symbol	Parameter	FQP6N90C	FQPF6N90C	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.75	2.25	°C/W	
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ, Max.	0.5		°C/W	
R _{θJA}	Thermal Resistance, Junction-to-Ambient, Max.	62.5	62.5	°C/W	

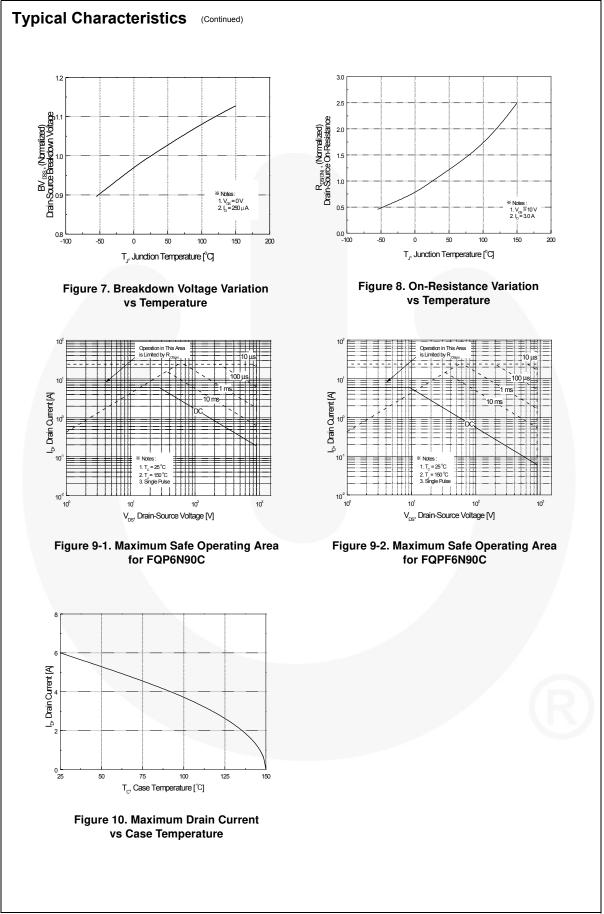
December 2013

		Top Mark	Pack	age	Packing	Method	Reel S	Size	Tape Wi	dth	Quantity	
		FQP6N90C	TO-	220 Tube N/A		Ą	N/A		50 units			
		20F Tube N/			4	N/A		50 units				
lectric	cal Cha	racteristics	T _C = 25°C	C unless ot	herwise noted							
Symbol		Parameter			Test Con	ditions		Min.	Тур.	Max.	Unit	
Off Cha	racterist	ics										
BV _{DSS}	Drain-Source Breakdown Voltage		V _{GS} = 0 V, I _D = 250 μA			900			V			
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient		$I_D = 250 \ \mu\text{A}$, Referenced to 25°C					1.07		V/°C		
DSS	Zero Gate Voltage Drain Current		V _{DS} = 900 V, V _{GS} = 0 V					10	μA			
000			V _{DS} = 720 V, T _C = 125°C						100	μA		
GSSF	Gate-Bod	Gate-Body Leakage Current, Forward		$V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$						100	nA	
GSSR	Gate-Bod	y Leakage Current,	Reverse		-30 V, V _{DS}					-100	nA	
On Cha	racterist	ics										
V _{GS(th)}	-	shold Voltage		V _{DS} =	V_{GS} , $I_D = 2$	250 μΑ		3.0		5.0	V	
R _{DS(on)}	Static Dra On-Resist			V _{GS} =	10 V, I _D = 3	3 A			1.93	2.3	Ω	
9 _{FS}	Forward T	Forward Transconductance			V _{DS} = 50 V, I _D = 3 A				5.5		S	
Dynam i C _{iss}	ic Charao Input Cap	cteristics	_		05.1/11	0.1/			1360	1770	pF	
C _{OSS}	· ·	apacitance			$V_{DS} = 25 V, V_{GS} = 0$ f = 1.0 MHz	= 0 V,	ν,		110	145	pF	
C _{rss}	_	Fransfer Capacitanc	e						11	15	pF	
	I										F	
		acteristics Delay Time	_						35	80	ns	
d(on)	Turn-On F	,	-	V _{DD} = 450 V, I _D = 6 A,				90	190	ns		
r d(off)		Delay Time		R _G = 3	$R_G = 25 \Omega$ (Note 4)			55	120	ns		
d(off)	Turn-Off F	,					(Note 4)		60	130	ns	
ମ ପୁ	Total Gate			V -	720 \/ -	6 4			30	40	nC	
Q _{gs}		rce Charge			V _{DS} = 720 V, I _D = 6 A, V _{GS} = 10 V				9.0		nC	
Q _{gd}	Gate-Drai			V _{GS} = 10 V			(Note 4)		12		nC	
94	2			1								
Drain-S	ource Di	ode Characteri	istics a	nd Ma	ximum R	atinas						
s	Maximum Continuous Drain-Source Diode Forward Current						6.0	Α				
SM	Maximum	Aaximum Pulsed Drain-Source Diode Fo								24	A	
/ _{SD}		Irce Diode Forward		$V_{GS} = 0 V, I_S = 6 A$				1.4	V			
rr	Reverse F	Recovery Time	-	$V_{GS} = 0 V, I_S = 6 A,$ $dI_F / dt = 100 A/\mu s$				630		ns		
	Deverse	Recovery Charge					6.9		μC			

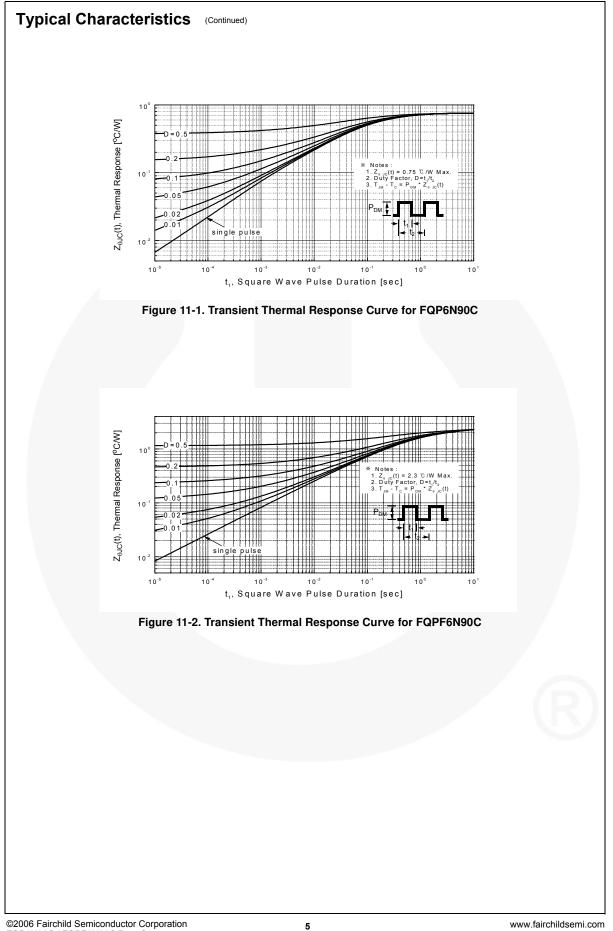
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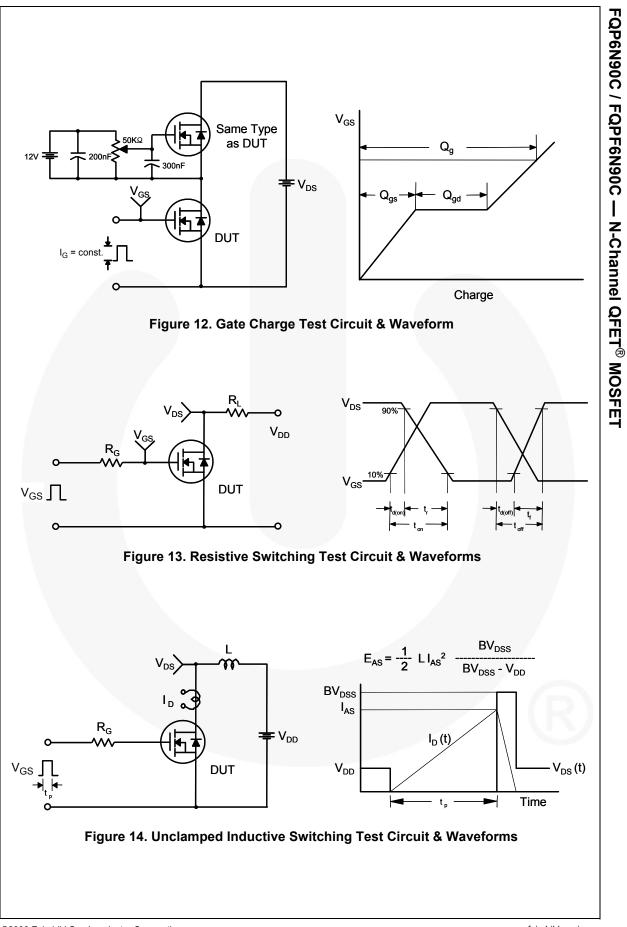


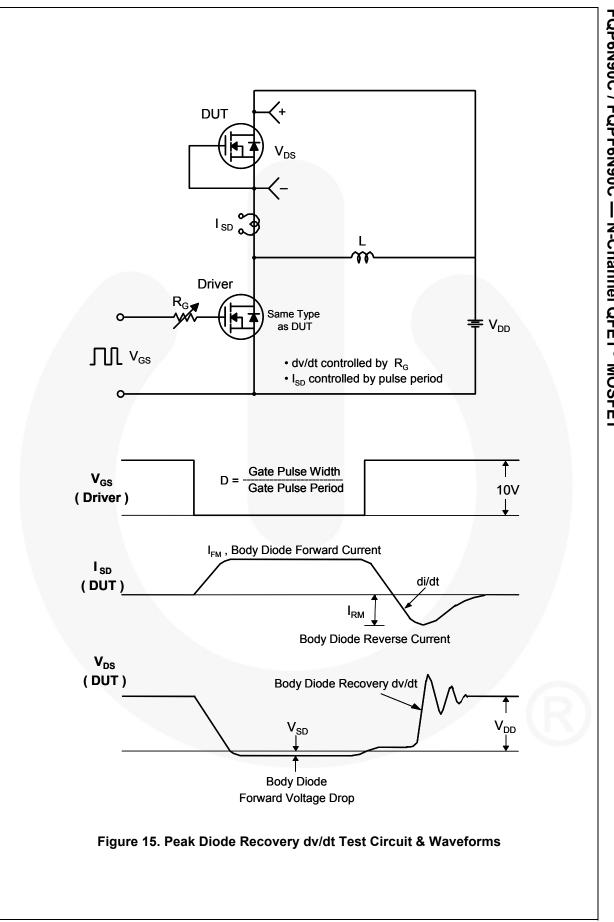
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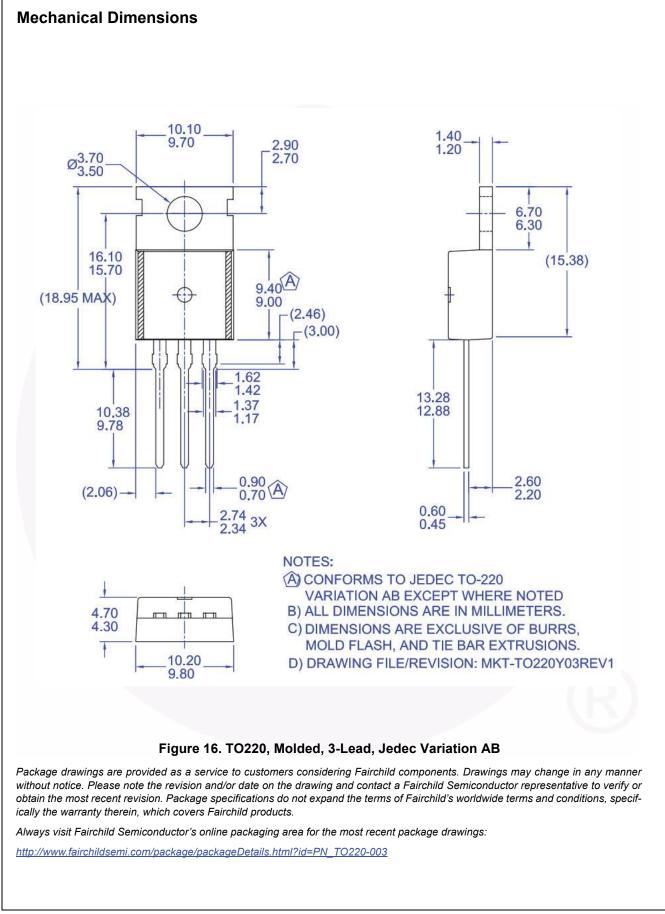


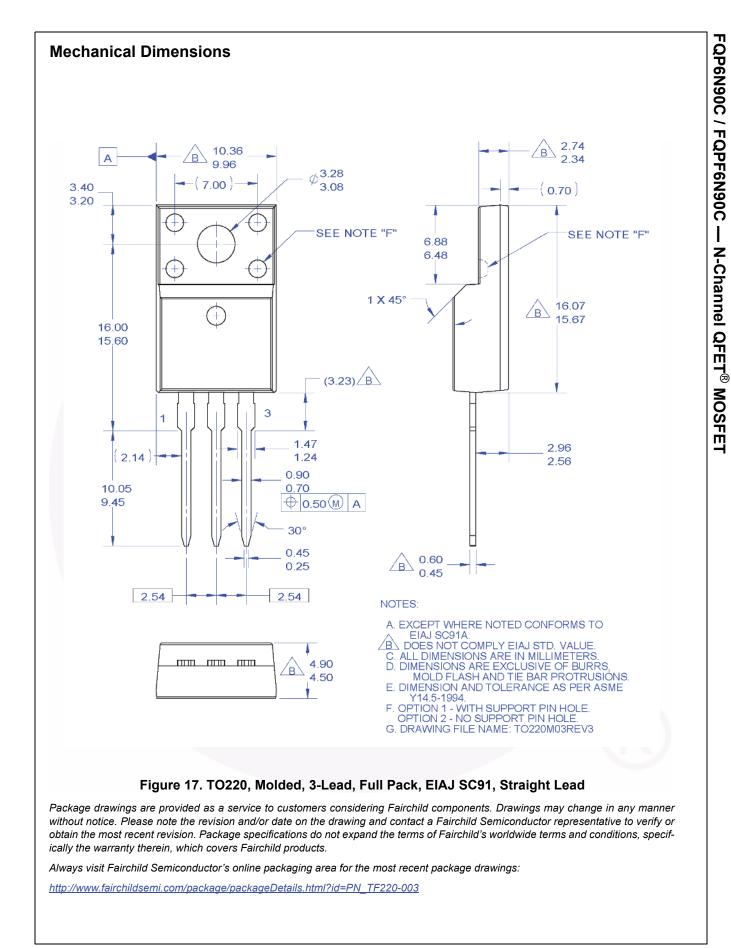
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notice to improve design.

Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.

Full Production

No Identification Needed

FQP6N90C / FQPF6N90C Rev. C1

Rev. 166

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